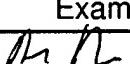


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE, METHOD OF MANUFACTURING THE SAME, AND SEMICONDUCTOR DEVICE						
<p>Application Number : Confirmation Number: First Named Applicant: Takahiro IIJIMA Attorney Docket Number: 021083a Art Unit: Examiner: Search string: (5796587).pn</p>							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
Ar	1	5796587	1998-08-18	Lauffer et al.		361	763
Signature							
Examiner Name				Date			
				12/08/04			



INFORMATION DISCLOSURE CITATION PTO-1449	Atty. Docket No. 021083A	Serial No. 10/709,912
	Applicant(s): IIJIMA, Takahiro, et al.	
	Filing Date: June 4, 2004	Group Art Unit: 2829

U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)
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_____	AB					
_____	AC					
_____	AD					
_____	AE					

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Translation (Yes or No)
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_____	AG			
_____	AH			
_____	AI			
_____	AJ			

OTHER DOCUMENTS

<u>AK</u>	AK	Nakamura et al.; "POLYIMIDE FILMS PREPARED BY ELECTROPHORETIC DEPOSITION AND THEIR DIELECTRIC BREAKDOWN", SPIE, Volume 2780, pages 71-75, September 11-14, 1995.
_____	AL	
Examiner	<u>M. M.</u>	Date Considered 12/08/04